



H4

Sheet 1 of 1

<b>Form PTO-1449</b> <b>U.S. DEPARTMENT OF COMMERCE</b> <b>PATENT AND TRADEMARK OFFICE</b>  <b>INFORMATION DISCLOSURE STATEMENT</b> <b>BY APPLICANT</b> (Use several sheets if necessary)	<b>ATTY. DKT. NO.</b> 219.40232X00	<b>SERIAL NO.</b> 10/077,967
	<b>APPLICANT</b> Sarah E. KIM et al.	
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## U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
	AA					
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## FOREIGN PATENT DOCUMENTS

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						Yes	No
	AM						
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	AT						

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Examiner Michael Trinkl		Date Considered 9/5/03